

thereof.  1. Name of conveying party(ies):  MAMORU HOSOYA YUZURU FUKUSHIMA HIDEKI SAKAI  2-14-02	Patent and Trademark Officerks: Please Record the attached original documents or copy  2. Name and address of receiving party(ies): Name: Sony Corporation
thereof.  1. Name of conveying party(ies):  MAMORU HOSOYA YUZURU FUKUSHIMA HIDEKI SAKAI  2-14-02	Name and address of receiving party(ies):
MAMORU HOSOYA YUZURU FUKUSHIMA HIDEKI SAKAI  2-14-0 Z	
	7-55, Kitasiiiiiagawa o-ciioiiie
JUNJI KUYAMA  Additional name(s) of conveying party(ies) attached?  □ Yes □ No	Shinagawa-ku, Tokyo 141, Japan Street Address:
3. Nature of conveyance:  △ Assignment	City:State:Zip: Additional Name(s) & Address(es) attached □ Yes ☒ No
4. Application (number(s) or patent number(s): If this document is being filed together with a new a	application, the execution date of the application is:
A. Patent Application No.(s) U.S. Serial No. 09/966,918_filed September Attorney Docket No. 09792909-5212	B: Patent No.(s) FEB 1 4 2000
Additional numbers attached? ☐ Yes ☒ No	-
5. Name and address of party to whom correspondence concerning document should be mailed:  SONNENSCHEIN NATH & ROSENTHAL	6. Total number of applications and patents involved  1  7. Total Fee (37 CFR 3.41 \$ 40.00  ⊠ Enclosed  ⊠ Authorized to be charged to deposit account any
P.O. Box #061080 Wacker Drive Station	Additional fees  8. Deposit Account Number:
Sears Tower Chicago, IL 60606-1080 Customer ID No. 26263	19.3140 (Attach duplicate copy of this page if paying by deposit account)
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David R. Metzger	January 30, 2002  Date  Total number of pages 3
<b>∖</b> Box	er sheet information to: f Patents and Trademarks Assignments gton, D.C. 20231+

**PATENT REEL: 012614 FRAME: 0869** 

09792909-5212

## Docket Number:

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in METHOD FOR PRODUCING CATHODE ACTIVE MATERIAL AND METHOD FOR PRODUCING

NON-AQUEOUS ELECTROLYTE CELL

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address:

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 09/966,918 Filing Date: Sep. 28, 2001

This assignment executed on the dates indicated below.

MAMORU HOSOYA		
Name of first or sole inventor	Execution date of U.S. Patent Application	
KANAGAWA, JAPAN		
Residence of first or sole inventor  Residence of first or sole inventor  Signature of first or sole inventor	Jan. 7, 2002	
Signature of first or sole inventor	Date of this assignment	

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YUZURU FUKUSHIMA	
Name of second inventor	Execution date of U.S. Patent Application
MIYAGI, JAPAN	
Residence of second inventor	
Signature of second inventor	Jan. 8, 2007.
Signature of second inventor	Jan. 8, 2002 Date of this assignment
HIDEKI SAKAI	
Name of third inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of third inventor	
Hideki Sakai	Jan. 25, 2002  Date of this assignment
Signature of third inventor	Date of this assignment
JUNJI KUYAMA	
Name of fourth inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of fourth inventor	,
min'i duyama	Pcc. 7.1 . 2001  Date of this assignment
Signature of fourth Inventor	Date of this assignment
	The All C Patent Application
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
	Date of this assignment
Signature of fifth inventor	Date of this dollars

**RECORDED: 02/14/2002** 

PATENT REEL: 012614 FRAME: 0871